



SBOS051B - OCTOBER 1995 - REVISED FEBRUARY 2005

Precision, Low Power INSTRUMENTATION AMPLIFIERS

FEATURES

LOW OFFSET VOLTAGE: 50µV max

LOW DRIFT: 0.5μV/°C max

LOW INPUT BIAS CURRENT: 5nA max

HIGH CMR: 120dB min

INPUTS PROTECTED TO ±40V

WIDE SUPPLY RANGE: ±2.25V to ±18V

LOW QUIESCENT CURRENT: 700µA

8-PIN PLASTIC DIP, SO-8

APPLICATIONS

- **BRIDGE AMPLIFIER**
- THERMOCOUPLE AMPLIFIER
- RTD SENSOR AMPLIFIER
- MEDICAL INSTRUMENTATION
- DATA ACQUISITION

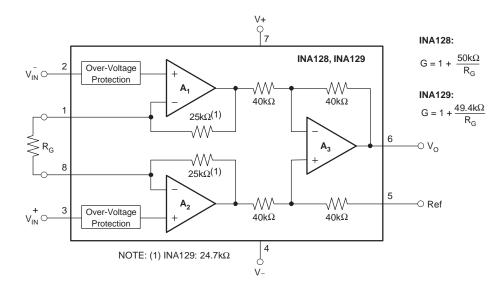
DESCRIPTION

The INA128 and INA129 are low power, general purpose instrumentation amplifiers offering excellent accuracy. The versatile 3-op amp design and small size make them ideal for a wide range of applications. Current-feedback input circuitry provides wide bandwidth even at high gain (200kHz at G = 100).

A single external resistor sets any gain from 1 to 10,000. The INA128 provides an industry-standard gain equation; the INA129 gain equation is compatible with the AD620.

The INA128/INA129 is laser trimmed for very low offset drift $(0.5\mu V/^{\circ}C)$ and high (50µV), common-mode rejection (120dB at G ≥ 100). It operates with power supplies as low as ±2.25V, and quiescent current is only 700µA—ideal for batteryoperated systems. Internal input protection can withstand up to ±40V without damage.

The INA128/INA129 is available in 8-pin plastic DIP and SO-8 surface-mount packages, specified for the -40°C to +85°C temperature range. The INA128 is also available in a dual configuration, the INA2128.





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ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage±18V
Analog Input Voltage Range±40V
Output Short-Circuit (to ground) Continuous
Operating Temperature40°C to +125°C
Storage Temperature Range55°C to +125°C
Junction Temperature
Lead Temperature (soldering, 10s) +300°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

ELECTROSTATIC DISCHARGE SENSITIVITY



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate

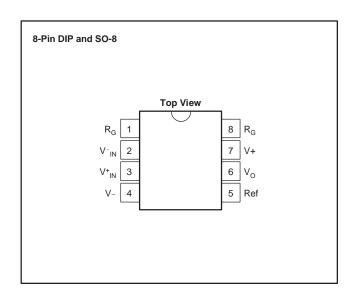
precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION

For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet.

PIN CONFIGURATION





ELECTRICAL CHARACTERISTICS

At $T_A = +25^{\circ}C,~V_S = \pm 15 V,~R_L = 10 k\Omega,$ unless otherwise noted.

At 1A = +25°C, VS = ±15V, KL = 1			INA128P, U INA129P. U			INA128PA, INA129PA,		
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
INPUT								
Offset Voltage, RTI								
Initial	T _A = +25°C		±10±100/G	±50±500/G		±25±100/G	±125±1000/G	μV
vs Temperature	$T_A = T_{MIN}$ to T_{MAX}		±0.2±2/G	±0.5±20/G		±0.2±5/G	±1±20/G	μV/°C
vs Power Supply	$V_S = \pm 2.25 \text{V to } \pm 18 \text{V}$		±0.2±20/G	±1±100/G		*	±2±200/G	μV/V
Long-Term Stability			±0.1±3/G			*		μV/mo
Impedance, Differential			10 ¹⁰ 2			*		Ω pF
Common-Mode			10 ¹¹ 9			*		Ω pF
Common-Mode Voltage Range(1)	$V_O = 0V$	(V+) - 2	(V+) - 1.4		*	*		V
		(V-) + 2	(V-) + 1.7		*	*		V
Safe Input Voltage				±40			*	V
Common-Mode Rejection	$V_{CM} = \pm 13V$, $\Delta R_S = 1k\Omega$							
-	G = 1	80	86		73	*		dB
	G = 10	100	106		93	*		dB
	G = 100	120	125		110	*		dB
	G = 1000	120	130		110	*		dB
BIAS CURRENT			±2	±5		*	±10	nA
vs Temperature			±30			*		pA/°C
Offset Current			±1	±5		*	±10	nA
vs Temperature			±30			*		pA/°C
NOISE VOLTAGE, RTI	$G = 1000, R_S = 0\Omega$							
f = 10Hz			10			*		nV/√ Hz
f = 100Hz			8			*		nV/√ Hz
f = 1kHz			8			*		nV/√ Hz
f _B = 0.1Hz to 10Hz			0.2			*		μ۷рр
Noise Current			İ					
f = 10Hz			0.9			*		pA/√ Hz
f = 1kHz			0.3			*		pA/√ Hz
f _B = 0.1Hz to 10Hz			30			*		рАрр
GAIN								F. FF
Gain Equation, INA128			1 + (50kΩ/R _G)			*		V/V
INA129			1 + (49.4kΩ/R _G)			*		V/V
Range of Gain		1	(10111111111111111111111111111111111111	10000	*		*	V/V
Gain Error	G = 1	•	±0.01	±0.024		*	±0.1	%
Can End	G = 10		±0.02	±0.4		*	±0.5	%
	G = 100		±0.02	±0.5		*	±0.7	%
	G = 1000		±0.55	±0.5		*	±0.7	%
Gain vs Temperature ⁽²⁾	G = 1000		±1	±10		*	*	ppm/°C
50kΩ (or 49.4kΩ) Resistance(2)(3))		±25	±100		*	*	ppm/°C
Nonlinearity	V _O = ±13.6V, G = 1		±0.0001	±0.001		*	±0.002	% of FSR
recimileanty	G = 10		±0.0001 ±0.0003	±0.001 ±0.002		*	±0.002 ±0.004	% of FSR
	G = 100		±0.0005	±0.002		*	±0.004 ±0.004	% of FSR
				±0.002 (4)		* *		
	G = 1000		±0.001	(7)		*	*	% of FSR

NOTE: * Specification is same as INA128P, U or INA129P, U. (1) Input common-mode range varies with output voltage — see typical curves. (2) Specified by wafer test. (3) Temperature coefficient of the $50k\Omega$ (or $49.4k\Omega$) term in the gain equation.

⁽⁴⁾ Nonlinearity measurements in G = 1000 are dominated by noise. Typical nonlinearity is $\pm 0.001\%$.



ELECTRICAL CHARACTERISTICS (continued) At $T_A = +25$ °C, $V_S = \pm 15$ V, $R_L = 10$ k Ω , unless otherwise noted.

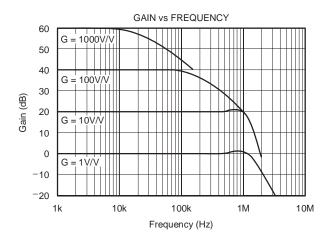
			INA128P, U INA129P. U			INA128PA, INA129PA,		
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
ОИТРИТ								
Voltage: Positive	$R_L = 10k\Omega$	(V+) - 1.4	(V+) - 0.9		*	*		V
Negative	$R_L = 10k\Omega$	(V-) + 1.4	(V-) + 0.8		*	*		V
Load Capacitance Stability			1000			*		pF
Short-Circuit Current			+6/–15			*		mA
FREQUENCY RESPONSE								
Bandwidth, -3dB	G = 1		1.3			*		MHz
	G = 10		700			*		kHz
	G = 100		200			*		kHz
	G = 1000		20			*		kHz
Slew Rate	$V_O = \pm 10V, G = 10$		4			*		V/μs
Settling Time, 0.01%	G = 1		7			*		μs
	G = 10		7			*		μs
	G = 100		9			*		μs
	G = 1000		80			*		μs
Overload Recovery	50% Overdrive		4			*		μs
POWER SUPPLY								
Voltage Range		±2.25	±15	±18	*	*	*	V
Current, Total	$V_{IN} = 0V$		±700	±750		*	*	μΑ
TEMPERATURE RANGE								
Specification		-40		+85	*		*	°C
Operating		-40		+125	*		*	°C
θ _{JA} 8-Pin DIP			80			*		°C/W
SO-8 SOIC			150			*		°C/W

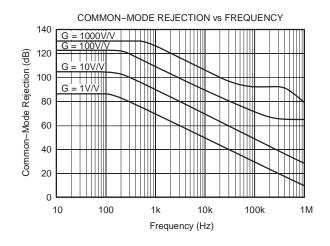
NOTE: * Specification is same as INA128P, U or INA129P, U. (1) Input common-mode range varies with output voltage — see typical curves. (2) Specified by wafer test. (3) Temperature coefficient of the $50k\Omega$ (or $49.4k\Omega$) term in the gain equation. (4) Nonlinearity measurements in G = 1000 are dominated by noise. Typical nonlinearity is $\pm 0.001\%$.

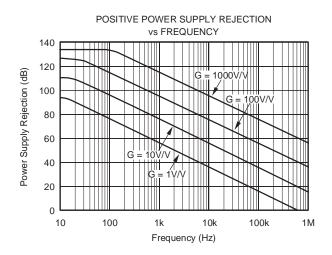


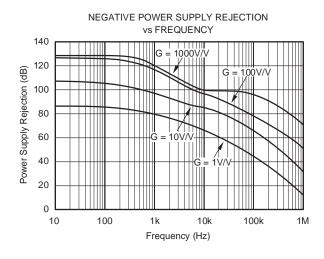
TYPICAL CHARACTERISTICS

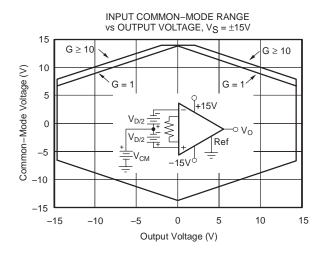
At $T_A = +25^{\circ}C$, $V_S = \pm 15V$, unless otherwise noted.

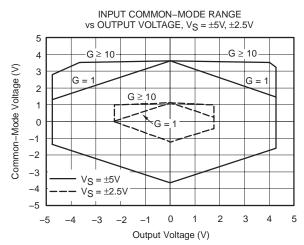








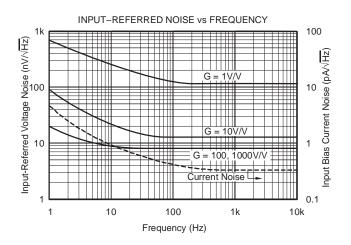


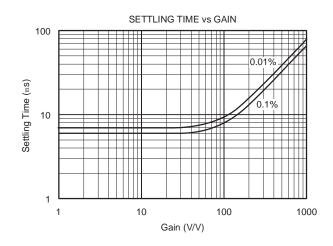


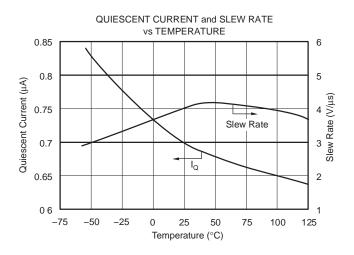


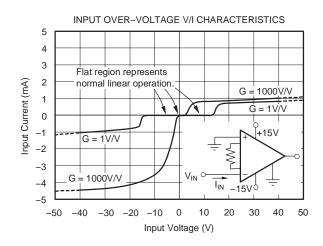
TYPICAL CHARACTERISTICS (continued)

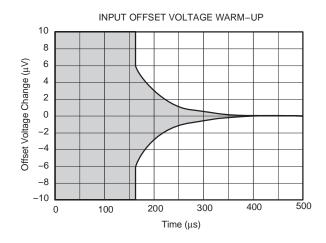
At $T_A = +25$ °C, $V_S = \pm 15$ V, unless otherwise noted.

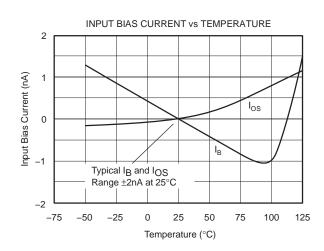








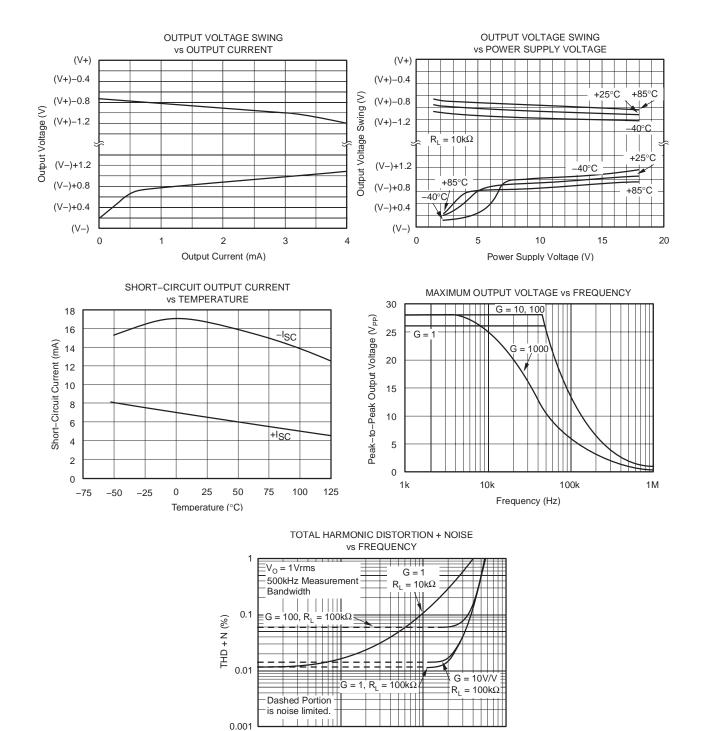






TYPICAL CHARACTERISTICS (continued)

At $T_A = +25$ °C, $V_S = \pm 15$ V, unless otherwise noted.



100

1k

10k

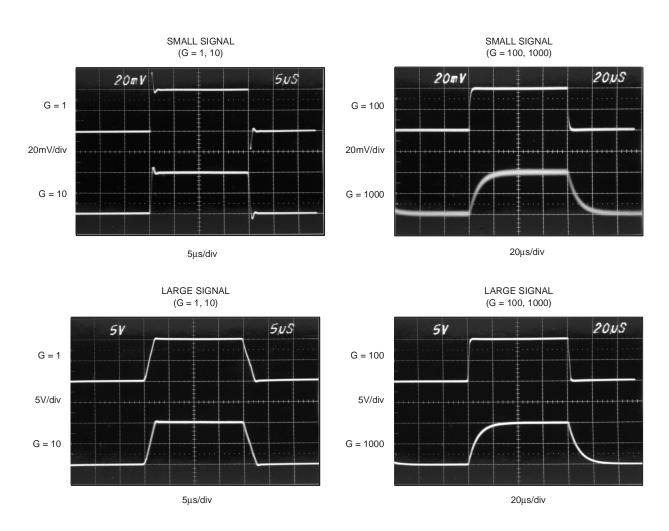
Frequency (Hz)

100k

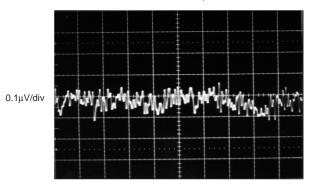


TYPICAL CHARACTERISTICS (continued)

At $T_A = +25^{\circ}C$, $V_S = \pm 15V$, unless otherwise noted.









APPLICATIONS INFORMATION

Figure 1 shows the basic connections required for operation of the INA128/INA129. Applications with noisy or high impedance power supplies may require decoupling capacitors close to the device pins as shown.

The output is referred to the output reference (Ref) terminal which is normally grounded. This must be a low-impedance connection to assure good common-mode rejection. A resistance of 8Ω in series with the Ref pin will cause a typical device to degrade to approximately 80dB CMR (G = 1).

SETTING THE GAIN

Gain is set by connecting a single external resistor, R_G, connected between pins 1 and 8:

INA128:

$$G = 1 + \frac{50k\Omega}{R_G}$$
 (1)

INA129:

$$G = 1 + \frac{49.4k\Omega}{R_G}$$
 (2)

Commonly used gains and resistor values are shown in Figure 1.

The $50k\Omega$ term in Equation 1 (49.4k Ω in Equation 2) comes from the sum of the two internal feedback resistors of A₁ and A₂. These on-chip metal film

resistors are laser trimmed to accurate absolute values. The accuracy and temperature coefficient of these internal resistors are included in the gain accuracy and drift specifications of the INA128/INA129.

The stability and temperature drift of the external gain setting resistor, R_G , also affects gain. R_G 's contribution to gain accuracy and drift can be directly inferred from the gain equation (1). Low resistor values required for high gain can make wiring resistance important. Sockets add to the wiring resistance which will contribute additional gain error (possibly an unstable gain error) in gains of approximately 100 or greater.

DYNAMIC PERFORMANCE

The typical performance curve *Gain vs Frequency* shows that, despite its low quiescent current, the INA128/INA129 achieves wide bandwidth, even at high gain. This is due to the current-feedback topology of the input stage circuitry. Settling time also remains excellent at high gain.

NOISE PERFORMANCE

The INA128/INA129 provides very low noise in most applications. Low frequency noise is approximately $0.2\mu V_{PP}$ measured from 0.1 to 10Hz (G \geq 100). This provides dramatically improved noise when compared to state-of-the-art chopper-stabilized amplifiers.

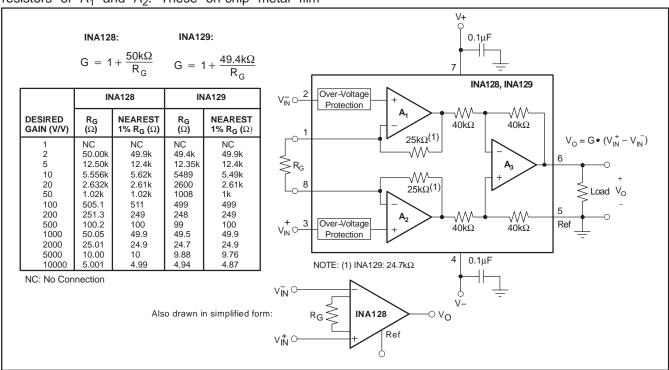


Figure 1. Basic Connections



OFFSET TRIMMING

The INA128/INA129 is laser trimmed for low offset voltage and offset voltage drift. Most applications require no external offset adjustment. Figure 2 shows an optional circuit for trimming the output offset voltage. The voltage applied to Ref terminal is summed with the output. The op amp buffer provides low impedance at the Ref terminal to preserve good common-mode rejection.

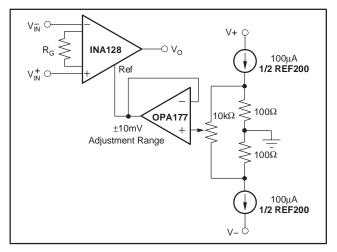


Figure 2. Optional Trimming of Output Offset Voltage

INPUT BIAS CURRENT RETURN PATH

The input impedance of the INA128/INA129 is extremely high—approximately $10^{10}\Omega$. However, a path must be provided for the input bias current of both inputs. This input bias current is approximately $\pm 2nA$. High input impedance means that this input bias current changes very little with varying input voltage.

Input circuitry must provide a path for this input bias current for proper operation. Figure 3 shows various provisions for an input bias current path. Without a bias current path, the inputs will float to a potential which exceeds the common-mode range, and the input amplifiers will saturate.

If the differential source resistance is low, the bias current return path can be connected to one input (see the thermocouple example in Figure 3). With higher source impedance, using two equal resistors provides a balanced input with possible advantages of lower input offset voltage due to bias current and better high-frequency common-mode rejection.

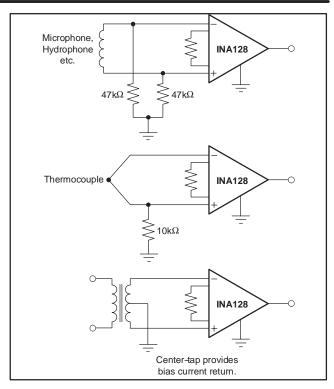


Figure 3. Providing an Input Common-Mode Current Path

INPUT COMMON-MODE RANGE

The linear input voltage range of the input circuitry of the INA128/INA129 is from approximately 1.4V below the positive supply voltage to 1.7V above the negative supply. As a differential input voltage causes the output voltage increase, however, the linear input range will be limited by the output voltage swing of amplifiers A_1 and A_2 . So the linear common-mode input range is related to the output voltage of the complete amplifier. This behavior also depends on supply voltage—see performance curves, *Input Common-Mode Range vs Output Voltage*.

Input-overload can produce an output voltage that appears normal. For example, if an input overload condition drives both input amplifiers to their positive output swing limit, the difference voltage measured by the output amplifier will be near zero. The output of A_3 will be near 0V even though both inputs are overloaded.

LOW VOLTAGE OPERATION

The INA128/INA129 can be operated on power supplies as low as ± 2.25 V. Performance remains excellent with power supplies ranging from ± 2.25 V to ± 18 V. Most parameters vary only slightly throughout this supply voltage range—see typical performance curves.



Operation at very low supply voltage requires careful attention to assure that the input voltages remain within their linear range. Voltage swing requirements of internal nodes limit the input common-mode range with low power supply voltage. Typical performance curves, "Input Common-Mode Range vs Output Voltage" show the range of linear operation for ± 15 V, ± 5 V, and ± 2.5 V supplies.

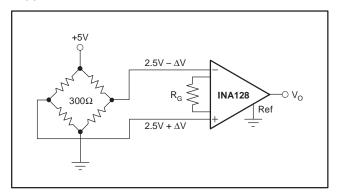


Figure 4. Bridge Amplifier

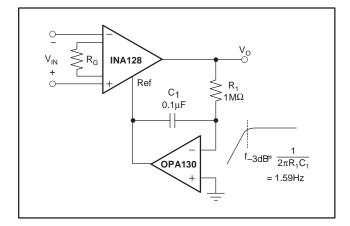


Figure 5. AC-Coupled Instrumentation Amplifier

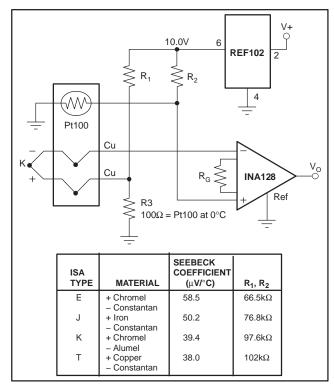


Figure 6. Thermocouple Amplifier with RTD Cold-Junction Compensation

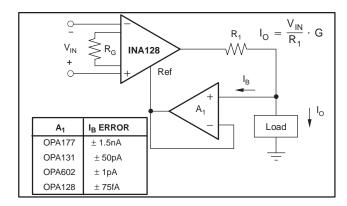


Figure 7. Differential Voltage to Current Converter

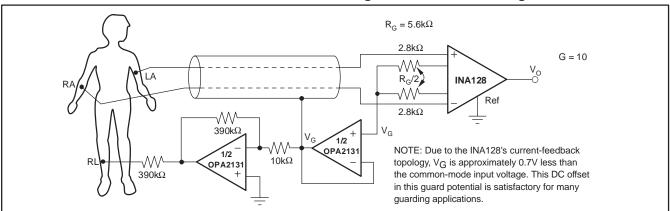


Figure 8. ECG Amplifier with Right-Leg Drive





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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
INA128P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		INA128P	Samples
INA128PA	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		INA128P A	Samples
INA128PAG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		INA128P A	Samples
INA128PG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		INA128P	Samples
INA128U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 128U	Samples
INA128U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 128U	Samples
INA128U/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 128U	Samples
INA128UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	INA 128U A	Samples
INA128UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	INA 128U A	Samples
INA128UA/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	INA 128U A	Samples
INA128UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	INA 128U A	Samples
INA128UAE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	INA 128U A	Samples
INA128UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	INA 128U A	Samples
INA128UG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 128U	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
INA129P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		INA129P	Sample
INA129PA	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		INA129P A	Sample
INA129PAG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		INA129P A	Sample
INA129PG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		INA129P	Sample
INA129U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 129U	Sampl
INA129U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 129U	Sampl
INA129U/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 129U	Sampl
INA129UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	INA 129U A	Sampl
INA129UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	INA 129U A	Samp
INA129UA/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	INA 129U A	Samp
INA129UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	INA 129U A	Samp
INA129UAE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	INA 129U A	Samp
INA129UG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 129U	Samp
SN412014DRE4	ACTIVE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125		Samp

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.



PACKAGE OPTION ADDENDUM



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PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF INA128, INA129:

Enhanced Product: INA129-EP

NOTE: Qualified Version Definitions:

• Enhanced Product - Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All difficults are nomina	ı											
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA128U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
INA128UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
INA129U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
INA129UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA128U/2K5	SOIC	D	8	2500	367.0	367.0	35.0
INA128UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
INA129U/2K5	SOIC	D	8	2500	367.0	367.0	35.0
INA129UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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